

Art Unit: 3651

CLMPTO

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D.T

Claims 1-13 and 18-26 Cancelled.

14. A method of wafer processing, comprising the steps of:  
randomizing a wafer lot by transporting individual wafers thereof  
variously,  
within a processing tool,  
from a processing position to a wafer cassette,  
from a wafer staging area to a wafer cassette,  
or from said processing position to said wafer staging area.
15. The method of Claim 14, further comprising the contemporaneous  
step of recording process sequence data for said wafers.
16. The method of Claim 14, further comprising the subsequent step  
of correlating fault and/or parametric data with process sequence  
data resulting from said randomization step.
17. The method of Claim 14, further comprising the subsequent step  
of correlating fault and/or parametric data with process sequence  
data resulting from said randomization step, and controlling  
process parameters accordingly.